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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/537,509	11/30/2005	Fumitsugu Fukuyo	046124-5388	4531
23973 DRINKER BII	7590 05/25/2007	EXAMINER		
DRINKER BIDDLE & REATH ATTN: INTELLECTUAL PROPERTY GROUP			GREENE, JAIRUS K	
ONE LOGAN 18TH AND CH	SQUARE HERRY STREETS		ART UNIT	PAPER NUMBER
PHILADELPHIA, PA 19103-6996		2891		
			MAIL DATE	DELIVERY MODE
			05/25/2007	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)					
	10/537,509	FUKUYO ET AL.					
Office Action Summary	Examiner	Art Unit					
	Jairus K. Greene	. 2809					
The MAILING DATE of this communic Period for Reply	cation appears on the cover sheet w	th the correspondence address					
A SHORTENED STATUTORY PERIOD FOWHICHEVER IS LONGER, FROM THE MADE - Extensions of time may be available under the provisions of after SIX (6) MONTHS from the mailing date of this community of the provision of t	ALING DATE OF THIS COMMUNION of 37 CFR 1.136(a). In no event, however, may a rinication. utory period will apply and will expire SIX (6) MON rill, by statute, cause the application to become AB	CATION. reply be timely filed ITHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).					
Status	•						
1) Responsive to communication(s) filed	I on <u>03 June 2005</u> .						
2a) ☐ This action is FINAL .							
3) Since this application is in condition for	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
closed in accordance with the practic	e under <i>Ex parte Quayle</i> , 1935 C.D). 11, 453 O.G. 213.					
Disposition of Claims							
4)⊠ Claim(s) <u>1-41</u> is/are pending in the ap	polication.						
	4a) Of the above claim(s) is/are withdrawn from consideration.						
5) Claim(s) is/are allowed.							
6) Claim(s) is/are rejected.							
7) Claim(s) is/are objected to.							
8) Claim(s) <u>1-41</u> are subject to restriction	n and/or election requirement.						
Application Papers							
9)☐ The specification is objected to by the	Examiner.						
10)⊠ The drawing(s) filed on <u>03 June 2005</u>		cted to by the Examiner.					
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
Replacement drawing sheet(s) including t	the correction is required if the drawing	(s) is objected to. See 37 CFR 1.121(d).					
11) The oath or declaration is objected to	by the Examiner. Note the attached	Office Action or form PTO-152.					
Priority under 35 U.S.C. § 119							
12)⊠ Acknowledgment is made of a claim for a)⊠ All b) Some * c) None of:	or foreign priority under 35 U.S.C. §	; 119(a)-(d) or (f).					
1. Certified copies of the priority documents have been received.							
2. Certified copies of the priority documents have been received in Application No							
3. Copies of the certified copies o	f the priority documents have been	received in this National Stage					
application from the Internation	al Bureau (PCT Rule 17.2(a)).						
* See the attached detailed Office action	for a list of the certified copies not	received.					
Attachment(s)		Commence (DTO 442)					
 Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PT 		Summary (PTO-413) s)/Mail Date					
3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date <u>See Continuation Sheet.</u>		nformal Patent Application —					

DETAILED ACTION

Election/Restrictions

1. This application contains claims directed to the following five patentably distinct species: method of singulation wherein the substrate modified region is molten or a void, method of singulation wherein the fracture reaches the front and/or backside of the substrate, a method of singulation comprising grinding the rear face of the substrate, method of singulation wherein the laser light entrance surface is the rear face of the substrate, and a method of singulation wherein the singulated chip is picked up or removed from the singulation tape for mounting. The first and second aforementioned species are independent and distinct because, stealth dicing to generate a molten region or void versus a fracture within substrate encompass qualitatively and physically different laser and singulation application approach, technique, and results – particularly since applying mechanical (tensile) stress by expanding the tape will serve to heat the inner substrate as opposed to facilitating the creation of cracks (which is different than facilitating crack propagation). The first or second singulation method and the methods comprising grinding the rear surface of the substrate, using the rear surface of the substrate for laser exposure and picking the wafer up do not necessarily have to been in conjunction with each other to achieve the desired product. Hence they will be considered mutually exclusive species of the disclosed invention.

Applicant is required under 35 U.S.C. 121 to elect a single disclosed species for prosecution on the merits to which the claims shall be restricted if no generic claim is

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finally held to be allowable. Currently, the generic claim of this invention reads as

follows:

A method of cutting a semiconductor substrate, the method comprising the steps of: irradiating a semiconductor substrate having a sheet bonded thereto by way of a diebonding resin layer with laser light while locating a light-converging point within the semiconductor substrate, so as to form a modified region caused by photon absorption within the semiconductor substrate, and causing the modified region to form a part which is intended to be cut; and expanding the sheet after the step of forming the part which is intended to be cut, so as to cut the semiconductor substrate and die-bonding resin layer along the part which is intended to be cut.

Applicant is advised that a reply to this requirement must include an identification of the species that is elected consonant with this requirement, and a listing of all claims readable thereon, including any claims subsequently added. An argument that a claim is allowable or that all claims are generic is considered nonresponsive unless accompanied by an election.

Upon the allowance of a generic claim, applicant will be entitled to consideration of claims to additional species which depend from or otherwise require all the limitations of an allowable generic claim as provided by 37 CFR 1.141. If claims are added after the election, applicant must indicate which are readable upon the elected species.

MPEP § 809.02(a).

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jairus K. Greene whose telephone number is (571) 270-1747. The examiner can normally be reached on Monday thru Friday, 7:30am-5:00pm EST.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David Bruce can be reached on (571) 272-2487. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

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DAVID BRUCE
SUBERVISORY PATENT EXAMINER

JKG